

DESIGN INFORMATION

MIN. TRACK WIDTH:

10

MIL

MIN. CLEARANCE:

5

MIL

MIN. VIA PAD SIZE:

27

MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

☐ FR-408

☒ FR-4 High Tg

☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10%

☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN

☒ NC_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um

☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP

☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE

☐ OTHER

SOLDER RESIST COLOR: ☒ GREEN

☐ OTHER

☒ MATTE

☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)

☐ ENEPIG

☐ IMM. TIN/SILVER OR EQUIV

☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE

☐ N.C. ROUTE

☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS ->

☐ 1

☒ 2

☐ 3

☒ RoHS

☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

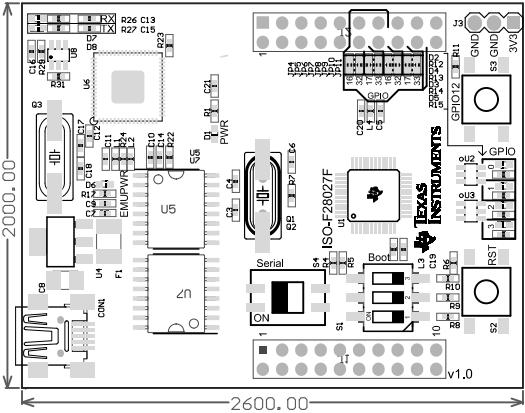
MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE

☒ REQUIRED

☐ PER ORDER

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top	Copper	1.38mil		
4	Dielectric 1	FR-4	59.05mil	4.8	
5	Bottom	Copper	1.38mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



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